

Thermal Pad APT2012



High Performance Thermal Pad



- Non-conducting
- Non-capacitive
- Very simple application
- Protection for sensitive processor chips
- Non-adhesive

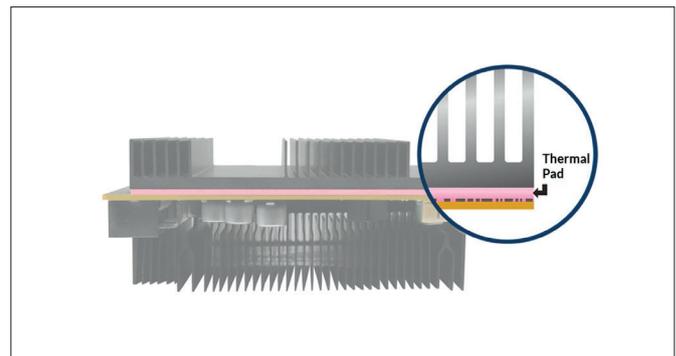
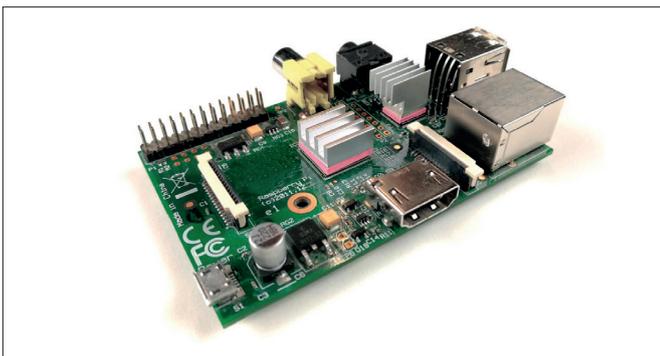
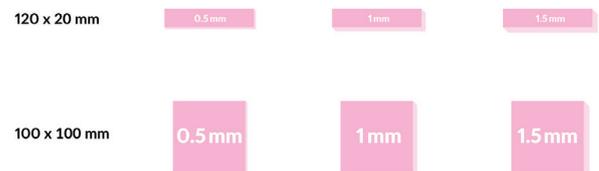
The ARCTIC Thermal Pad provides an efficient thermal interface between heat sinks and electronic devices where uneven surface topography, air gaps and rough surface textures are present. The silicon based material outperforms generic pads by far, is flexible and adaptive and thus works also at low pressure.

Specifications

General Characteristics	
Colour	Pink
Hardness: 0.5/1 mm Thickness	35 Shore OO
Hardness: 1 mm Thickness	20 Shore OO
Continuous Use Temperature	-40~150 °C
Specific Gravity	2.3 g/cc
Thermal conductivity	1.2 W/(m K)

Electrical Characteristics	
Dielectric Constant @1MHz	3.9
Volume Resistance	1 X 10 ¹² Ω-cm
Flammability Rating	UL 94 V-0

Dimensions	SKU
120x120 mm – 0.5 mm	ACTPD00023A
120x20 mm – 1 mm	ACTPD00024A
100x100 mm – 0.5 mm	ACTPD00020A
100x100 mm – 1 mm	ACTPD00021A
100x100 mm – 1.5 mm	ACTPD00022A



Using thermal pads

Thermal pads can be easily cut to the desired shape and size and can be used to ensure adequate temperature transfer on, among other things, RAM heat sinks and single-board computers.

Bridging gaps

With its low rigidity and good compression properties, the thermal pad serves as a perfect gap filler and easily bridges uneven surfaces and air gaps.



Product Information



Manual